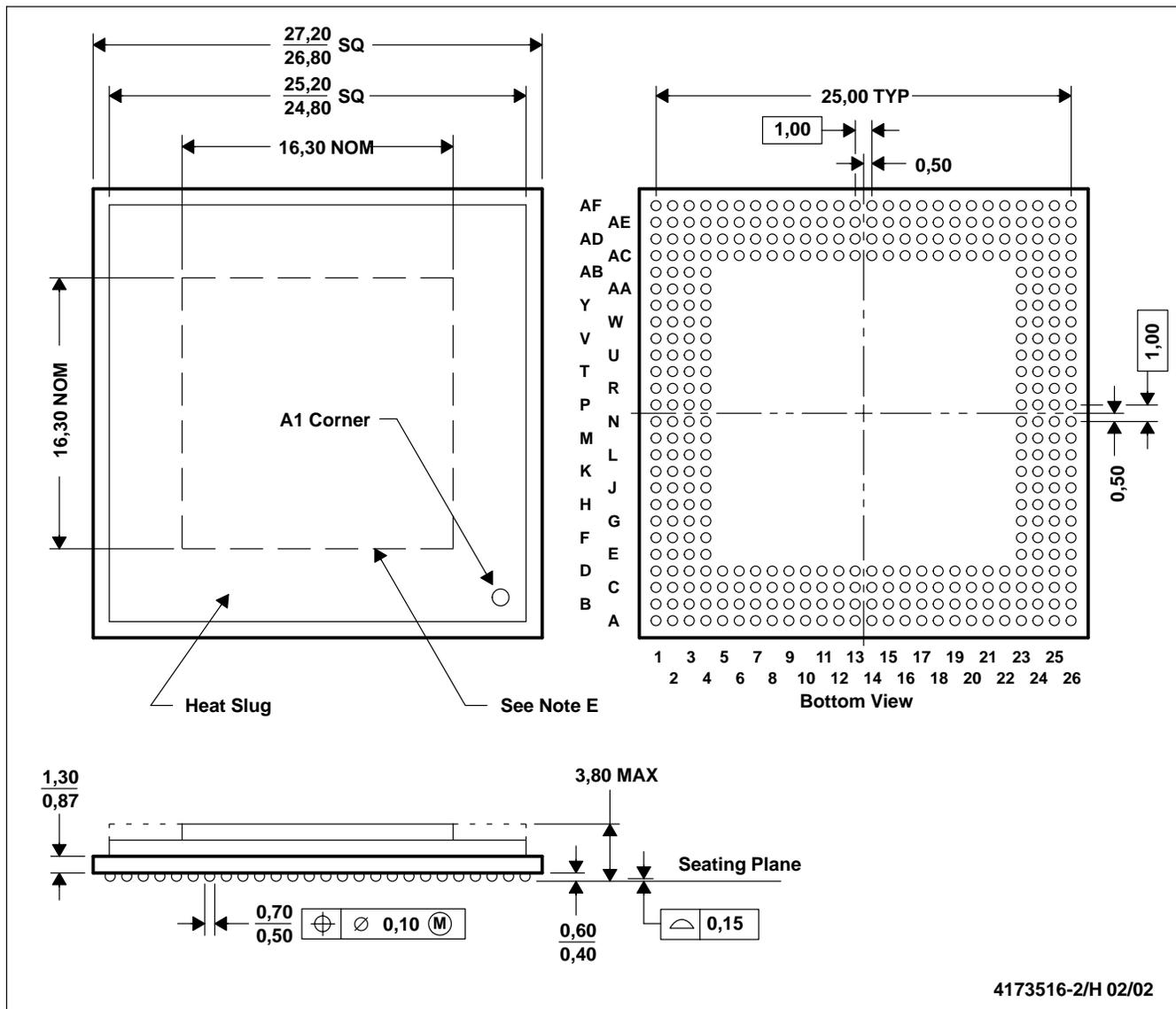


GJL (S-PBGA-N352)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Thermally enhanced plastic package with heat slug (HSL)
  - D. Flip chip application only
  - E. Possible protrusion in this area, but within 3,50 max package height specification
  - F. Falls within JEDEC MO-151/AAL-1

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### Mailing Address:

Texas Instruments  
Post Office Box 655303  
Dallas, Texas 75265